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Yamazaki et al. (43) **Pub. Date: Jul. 17, 2003**(54) **METHOD FOR FABRICATING
SEMICONDUCTOR DEVICE****Publication Classification**(51) **Int. Cl.⁷** **H01L 21/00**; H01L 21/30;
H01L 21/46(52) **U.S. Cl.** **438/455**; 438/458; 438/22(76) Inventors: **Shunpei Yamazaki**, Tokyo (JP);
Masakazu Murakami, Kanagawa (JP);
Toru Takayama, Kanagawa (JP);
Junya Maruyama, Kanagawa (JP)(57) **ABSTRACT**

Correspondence Address:

FISH & RICHARDSON, PC
4350 LA JOLLA VILLAGE DRIVE
SUITE 500
SAN DIEGO, CA 92122 (US)

The object of the invention is to provide a method for fabricating a semiconductor device having a peeled layer bonded to a base material with curvature. Particularly, the object is to provide a method for fabricating a display with curvature, more specifically, a light emitting device having an OLED bonded to a base material with curvature. An external force is applied to a support originally having curvature and elasticity, and the support is bonded to a peeled layer formed over a substrate. Then, when the substrate is peeled, the support returns into the original shape by the restoring force, and the peeled layer as well is curved along the shape of the support. Finally, a transfer object originally having curvature is bonded to the peeled layer, and then a device with a desired curvature is completed.

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